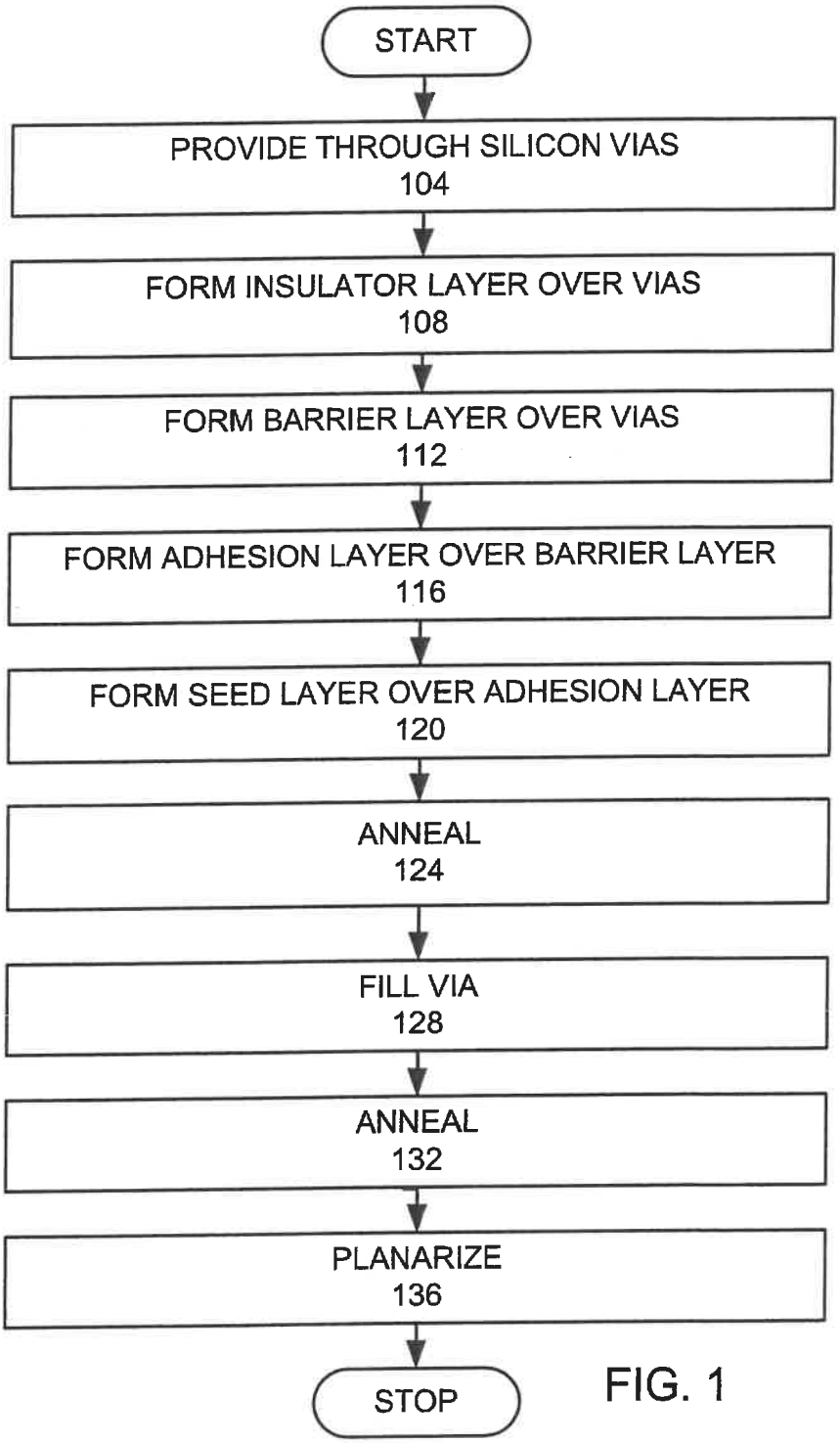
START
PROVIDE THROUGH SILICON VIAS
104
FORM INSULATOR LAYER OVER VIAS
108
FORM BARRIER LAYER OVER VIAS
112
FORM ADHESION LAYER OVER BARRIER LAYER
116
FORM SEED LAYER OVER ADHESION LAYER
120
ANNEAL
124
FILL VIA
128
ANNEAL
132
PLANARIZE
136
STOP

FIG. 1

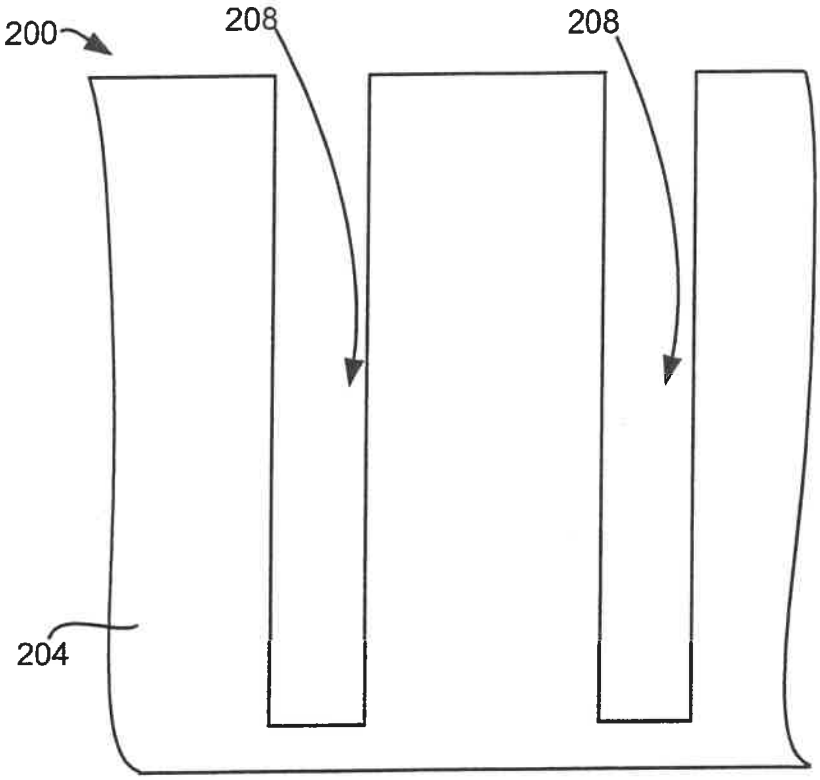

FIG. 2A

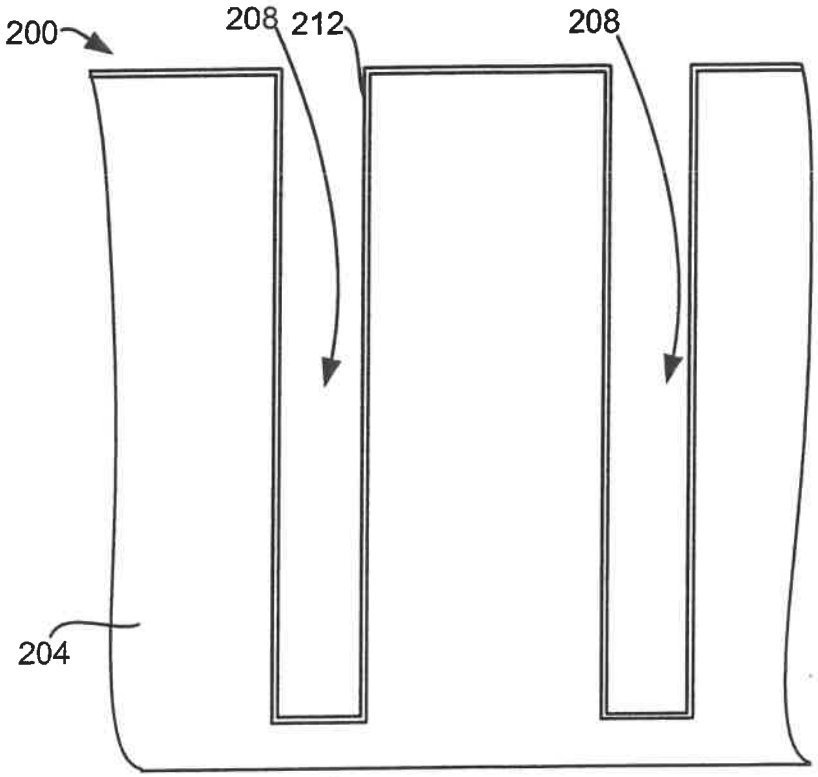

FIG. 2B

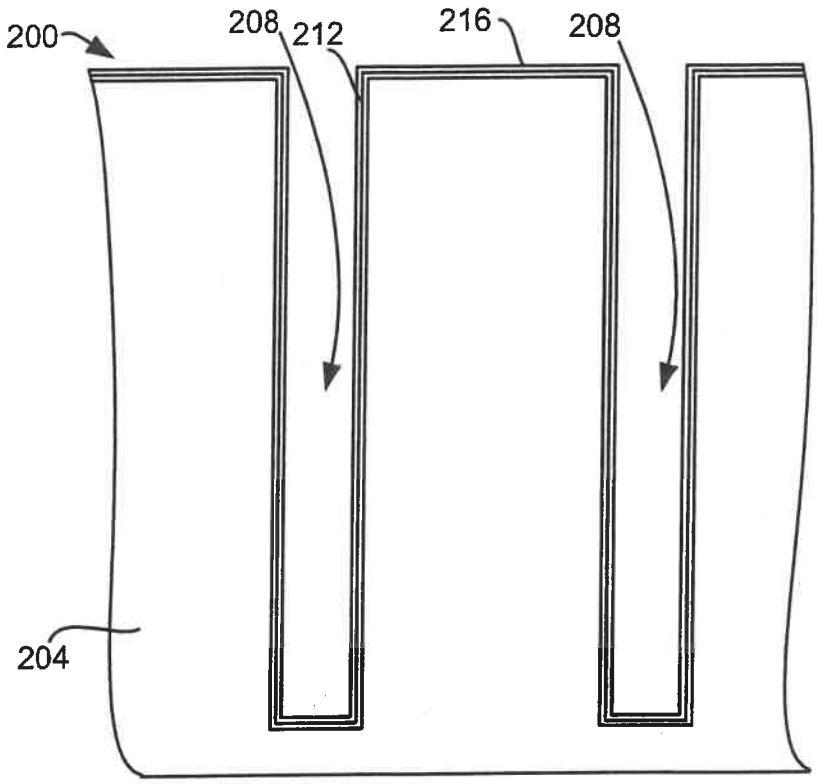

FIG. 2C

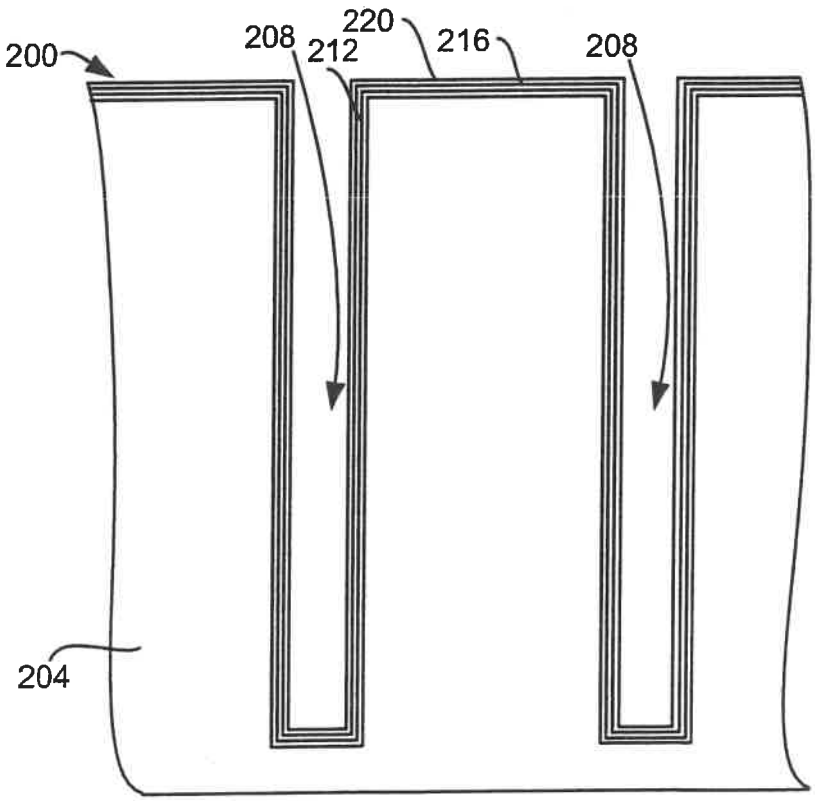

FIG. 2D

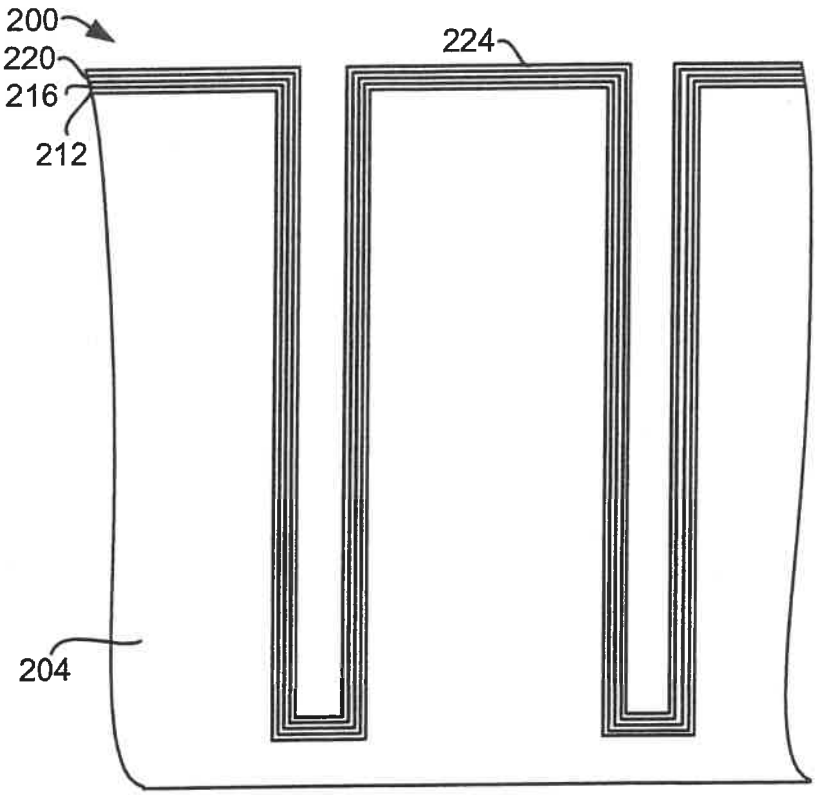

FIG. 2E

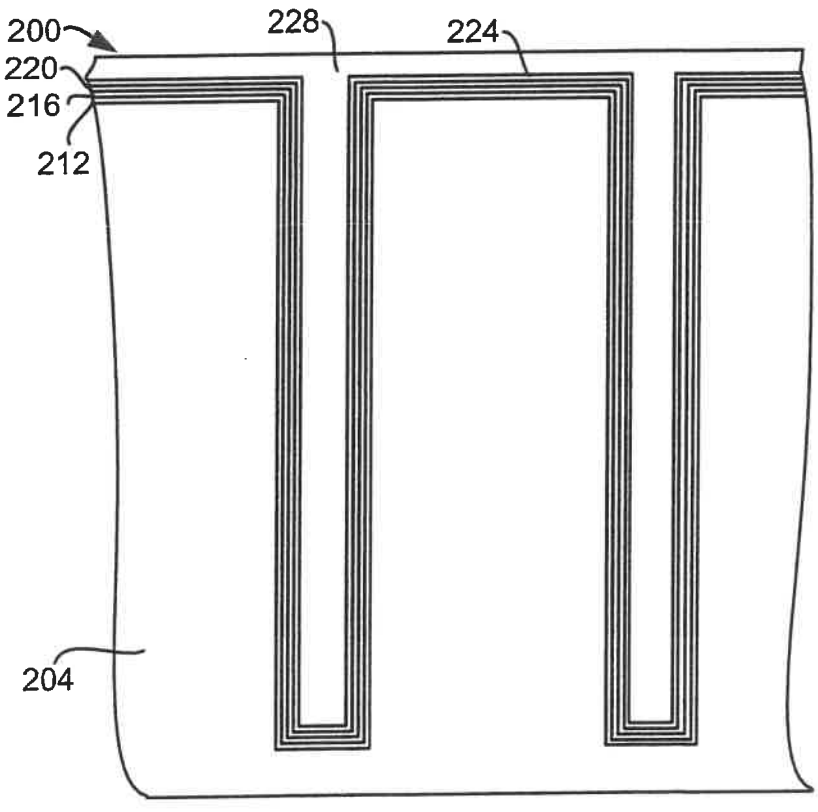

FIG. 2F

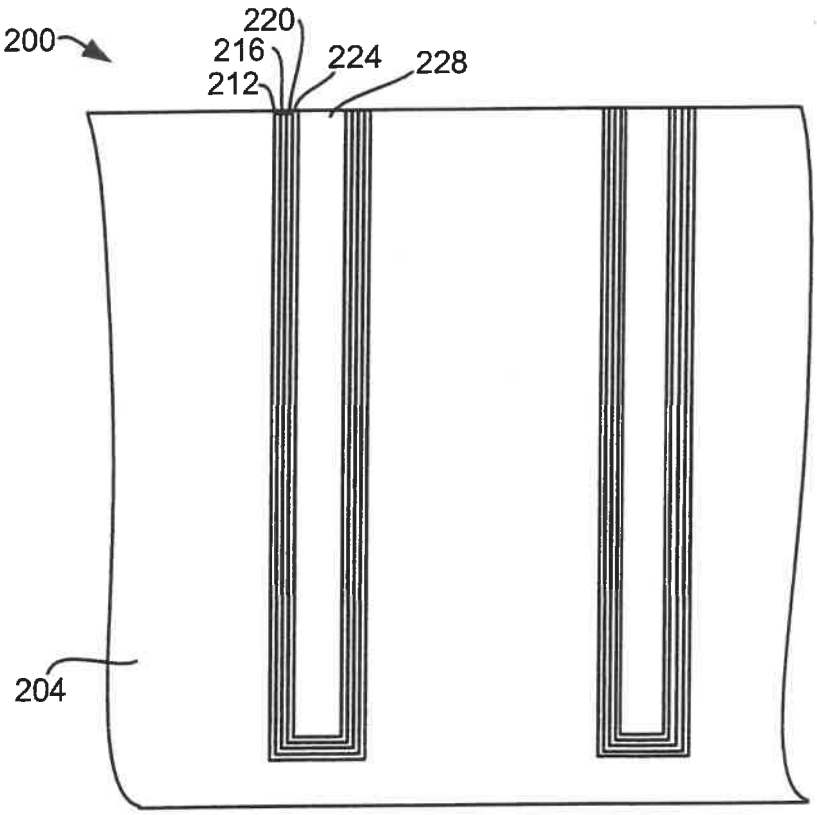

FIG. 2G